	In re Application of	Rowe		
	Application Number	r 09/660,824	Filed 9/13/	2000
	For A Mechanism Protocol	m to Survive Server Fai	lures When Usin	g The CIFS
	Group Art Unit 2126	Exami Hoang		
	der the provisions of 37 CFR 1.136(a	a) to extend the period f	or filing a	<u> </u>
The requested exter	lentified application. nsion and appropriate non-small-enti desired):	ty fee are as follows		
1		RE(EIVED	
	nonth (37 CFR 1.17(a)(1)) nonths (37 CFR 1.17(a)(2))	FEB	0 9 2004	\$ <u>110.00</u> \$ <u>420.00</u>
	months (37 CFR 1.17(a)(3))	Technology Center 2		
Four n	months (37 CFR 1.17(a)(4))			\$ <u>1,480.0</u>
Five m	nonths (37 CFR 1.17(a)(5))			\$ <u>2,010.0</u>
Applicant cl	laims small entity status. See 37 CF	R 1.27. Therefore the	ee amount show	'n
	duced by one-half, and the resulting the amount of the fee is enclosed.	tee is: \$.		
	y credit card. Form PTO-2038 is atta	ached		
The Comm	nissioner has already been authorized			
	to a Deposit Account.	·		
	nissioner is hereby authorized to char ny overpayment, to Deposit Account I osed a duplicate copy of this sheet.	ge any fees which may Number <u>50-0365</u> .	be required,	
I am the 🔲 a	applicant/inventor			
	assignee of record of the entire inter Statement under 37 CFR 3.73(b		TO/SB/96).	
	attorney or agent of record.	,		
	attorney or agent under 37 CFR 1.34 Registration number if acting under 37 C	4(a). CFB 1.34(a)		
WARNING: Inf be included on	formation on this form may becon n this form. Provide credit card in	ne public. Credit card	 information sho zation on PTO-2	ould not 2038.
1-29 -7	2004	ASue	enorstor	2
Date	e	Signat	ure	
		Steven A. Sy	vernofsky or printed name	

Burden Hour Statement: This form is estimated to take 0.1 hours to complete. Time will vary depending upon the needs of the individual case. Any comments on the amount of time you are required to complete this form should be sent to the Chief Information Officer, U.S. Patent and Trademark Office, Washington, DC 20231. DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. SEND TO: Assistant Commissioner for Patents, Washington, DC 20231.